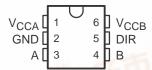
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- Available in the Texas Instruments
 NanoStar[™] and NanoFree[™] Packages
- Fully Configurable Dual-Rail Design Allows Each Port to Operate Over the Full 1.65-V to 5.5-V Power-Supply Range
- V_{CC} Isolation Feature If Either V_{CC} Input Is at GND, Both Ports Are in the High-Impedance State
- DIR Input Circuit Referenced to V_{CCA}
- Low Power Consumption, 4-μA Max I_{CC}
- ±24-mA Output Drive at 3.3 V

- I_{off} Supports Partial-Power-Down Mode Operation
- Max Data Rates
 - 420 Mbps (3.3-V to 5-V Translation)
 - 210 Mbps (Translate to 3.3 V)
 - 140 Mbps (Translate to 2.5 V)
 - 75 Mbps (Translate to 1.8 V)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE (TOP VIEW)



YEP OR YZP PACKAGE (BOTTOM VIEW)

A GND	03	40	В
GND	02	50	DIR
V _{CCA}	01	60	V _{CCB}

description/ordering information

This single-bit noninverting bus transceiver uses two separate configurable power-supply rails. The A port is designed to track V_{CCA}. V_{CCA} accepts any supply voltage from 1.65 V to 5.5 V. The B port is designed to track V_{CCB}. V_{CCB} accepts any supply voltage from 1.65 V to 5.5 V. This allows for universal low-voltage bidirectional translation between any of the 1.8-V, 2.5-V, 3.3-V, and 5-V voltage nodes.

The SN74LVC1T45 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input.

ORDERING INFORMATION

TA	PACKAGET	ORDERABLE PART NUMBER	TOP-SIDE MARKING‡	
TEL	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP	D1 - (0000	SN74LVC1T45YEPR	T 0
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	Reel of 3000	SN74LVC1T45YZPR	TA_
-40°C to 85°C	007 (007 00)	Reel of 3000	SN74LVC1T45DBVR	5.0
	SOT (SOT-23) – DBV	Reel of 250	SN74LVC1T45DBVT	CT1_
	COT (CO 70) DOI/	Reel of 3000	SN74LVC1T45DCKR	TA
	SOT (SC-70) – DCK	Reel of 250	SN74LVC1T45DCKT	TA_

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.

YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

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description/ordering information (continued)

The SN74LVC1T45 is designed so that the DIR input circuit is supplied by V_{CCA}.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

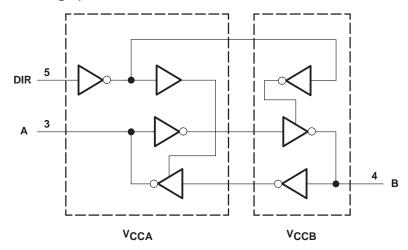
The V_{CC} isolation feature ensures that if either V_{CC} input is at GND, both ports are in the high-impedance state.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

FUNCTION TABLE

INPUT	OPERATION					
DIR	OPERATION					
L	B data to A bus					
Н	A data to B bus					

logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†
Supply voltage range, V_{CCA} and V_{CCB}
(see Note 1)
Voltage range applied to any output in the high or low state, VO
(see Notes 1 and 2): A port
B port
Input clamp current, I _{IK} (V _I < 0)
Output clamp current, I _{OK} (V _O < 0)
Continuous output current, IO ±50 mA
Continuous current through V _{CC} or GND ±100 mA
Package thermal impedance, θ _{JA} (see Note 3): DBV package
DCK package
YEP/YZP package
Storage temperature range, T _{stg} –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

- 2. The value of V_{CC} is provided in the recommended operating conditions table.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions (see Notes 4 through 8)

			VCCI	Vcco	MIN	MAX	UNIT
VCCA	0 1 1				1.65	5.5	.,
VCCB	Supply voltage				1.65	5.5	V
	•		1.65 V to 1.95 V		V _{CCI} × 0.65		
	High-level input	Data inputs	2.3 V to 2.7 V		1.7		l
VIH	voltage	(see Note 7)	3 V to 3.6 V		2		V
			4.5 V to 5.5 V		V _{CCI} × 0.7		
			1.65 V to 1.95 V			V _{CCI} ×0.35	
.,	Low-level input	Data inputs	2.3 V to 2.7 V			0.7] ,,
V_{IL}	voltage	(see Note 7)	3 V to 3.6 V			0.8	V
			4.5 V to 5.5 V			V _{CCI} ×0.3	
			1.65 V to 1.95 V		V _{CCA} × 0.65		
	High-level input	DIR	2.3 V to 2.7 V		1.7		1
VIH	voltage	(Referenced to V _{CCA}) (see Note 8)	3 V to 3.6 V		2		V
		(000110100)	4.5 V to 5.5 V		V _{CCA} ×0.7		
			1.65 V to 1.95 V			V _{CCA} × 0.35	
	Low-level input	DIR	2.3 V to 2.7 V			0.7	1
VIL	voltage	. I Referenced to VCCVI	3 V to 3.6 V			0.8	V
			4.5 V to 5.5 V			V _{CCA} ×0.3	1
VI	Input voltage	•			0	5.5	V
VO	Output voltage				0	Vcco	V
				1.65 V to 1.95 V		-4	
				2.3 V to 2.7 V		-8	
ЮН	High-level output curre	nt		3 V to 3.6 V		-24	mA
				4.5 V to 5.5 V		-32	
				1.65 V to 1.95 V		4	
				2.3 V to 2.7 V		8	
IOL	Low-level output currer	nt		3 V to 3.6 V		24	mA
				4.5 V to 5.5 V		32	
			1.65 V to 1.95 V			20	
			2.3 V to 2.7 V			20	1
Δt/Δν	Input transition rise or	Data input	3 V to 3.6 V			10	ns/V
	fall rate		4.5 V to 5.5 V			5	-7 -
		Control input	1.65 V to 5.5 V			5	
Ta	Operating free air terms	ı .	1.00 V 10 0.0 V		-40	85	°C
TA	Operating free-air temp	erature			-40	60	٠.

NOTES: 4. $V_{\mbox{CCI}}$ is the $V_{\mbox{CC}}$ associated with the data input port.

- 5. V_{CCO} is the V_{CC} associated with the output port.
- All unused data inputs of the device must be held at V_{CCI} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.
- 7. For V_{CCI} values not specified in the data sheet, $V_{IH(min)} = V_{CCI} \times 0.7 \text{ V}$, $V_{IL(max)} = V_{CCI} \times 0.3 \text{ V}$.
- 8. For V_{CCI} values not specified in the data sheet, $V_{IH(min)} = V_{CCA} \times 0.7 \text{ V}$, $V_{IL(max)} = V_{CCA} \times 0.3 \text{ V}$.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Notes 9 and 10)

						T,	Δ = 25°C	;	-40°C to	5°C 85°C	
PARAN	METER	TEST COND	DITIONS	VCCA	VCCB	MIN	TYP	MAX	MIN	MAX	UNIT
		$I_{OH} = -100 \mu A$,	$V_I = V_{IH}$	1.65 V to 4.5 V	1.65 V to 4.5 V				VCCO-0.	1	
		$I_{OH} = -4 \text{ mA},$	$V_I = V_{IH}$	1.65V	1.65 V				1.2		
Vон		$I_{OH} = -8 \text{ mA},$	$V_I = V_{IH}$	2.3 V	2.3 V				1.9		V
		$I_{OH} = -24 \text{ mA},$	$V_I = V_{IH}$	3 V	3 V				2.4		
		$I_{OH} = -32 \text{ mA},$	$V_I = V_{IH}$	4.5 V	4.5 V				3.8		
		$I_{OL} = 100 \mu A$,	$V_I = V_{IL}$	1.65 V to 4.5 V	1.65 V to 4.5 V					0.1	
		IOL = 4 mA,	$V_I = V_{IL}$	1.65 V	1.65 V					0.45	
V_{OL}		IOL = 8 mA,	VI = VIL	2.3 V	2.3 V					0.3	V
		I _{OL} = 24 mA,	VI = VIL	3 V	3 V					0.55	
		$I_{OL} = 32 \text{ mA},$	$V_I = V_{IL}$	4.5 V	4.5 V					0.55	
lį	DIR input	V _I = V _{CCA} or GN	ID	1.65 V to 5.5 V	1.65 V to 5.5 V			±1		±2	μΑ
	A port	., ., ., .	5.4	0 V	0 to 5.5 V			±1		±2	
loff	B port	V_I or $V_O = 0$ to 5	.5 V	0 to 5.5 V	0 V			±1		±2	μΑ
loz	A or B ports	VO = VCCO or G	SND	1.65 V to 5.5 V	1.65 V to 5.5 V			±1		±2	μΑ
				1.65 V to 5.5 V	1.65 V to 5.5 V					3	
ICCA		V _I = V _{CCI} or GND	$I_{O} = 0$	5.5 V	0 V					2	μΑ
		GIAD		0 V	5.5 V					0	
				1.65 V to 5.5 V	1.65 V to 5.5 V					3	
ICCB		$V_I = V_{CCI}$ or GND	$I_{O} = 0$	5.5 V	0 V					0	μΑ
		GIAD		0 V	5.5 V					2	
ICCA+	ІССВ	V _I = V _{CCI} or GND	I _O = 0	1.65 V to 5.5 V	1.65 V to 5.5 V					4	μΑ
	A port	A port at V _{CCA} -								50	
ΔICCA	DIR	DIR at V _{CCA} - 0 B port = OPEN, A port at V _{CCA} o	.6 V,	3 V to 5.5 V	3 V to 5.5 V					50	μΑ
ΔI _{CCB}	B port	B port at V _{CCB} -		3 V to 5.5 V	3 V to 5.5 V		_	_		50	μΑ
Ci	DIR input	V _I = V _{CCA} or GN	ID	3.3 V	3.3 V		2.5				pF
C _{io}	A or B ports	VO = VCCA/B o	r GND	3.3 V	3.3 V		6				pF

NOTES: 9. V_{CCO} is the V_{CC} associated with the output port. 10. V_{CCI} is the V_{CC} associated with the input port.

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switching characteristics over recommended operating free-air temperature range, V_{CCA} = 1.8 V \pm 0.15 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	V _{CCB} = 1.8 V ± 0.15 V		V _{CCB} = 2.5 V ± 0.2 V		V _{CCB} = 3.3 V ± 0.3 V		V _{CCB} = 5 V ± 0.5 V		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	А	В	3	17.7	2.2	10.3	1.7	8.3	1.4	7.2	ns
t _{PHL}	A	Ь	2.8	14.3	2.2	8.5	1.8	7.1	1.7	7	115
t _{PLH}	В	Α	3	17.7	2.3	16	2.1	15.5	1.9	15.1	ns
t _{PHL}	Ь	X	2.8	14.3	2.1	12.9	2	12.6	1.8	12.2	115
^t PHZ	DIR	А	5.2	19.4	4.8	18.5	4.7	18.4	5.1	17.1	20
t _{PLZ}	DIK	A	2.3	10.5	2.1	10.5	2.4	10.7	3.1	10.9	ns
^t PHZ	DIR	В	7.4	21.9	4.9	11.5	4.6	10.3	2.8	8.2	20
t _{PLZ}	DIK	Ь	4.2	16	3.7	9.2	3.3	8.4	2.4	6.4	ns
t _{PZH} †	DIR	۸		33.7		25.2		23.9		21.5	20
t _{PZL} †	DIR	Α		36.2		24.4		22.9		20.4	ns
t _{PZH} †	DIR			28.2		20.8		19		18.1	20
t _{PZL} †	DIK	В		33.7		27		25.5		24.1	ns

[†]The enable time is a calculated value, derived using the formula shown in the section entitled *enable times* on page 16.

switching characteristics over recommended operating free-air temperature range, V_{CCA} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	V _{CCB} = 1.8 V ± 0.15 V		V _{CCB} = 2.5 V ± 0.2 V		V _{CCB} = 3.3 V ± 0.3 V		V _{CCB} = 5 V ± 0.5 V		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	А	В	2.3	16	1.5	8.5	1.3	6.4	1.1	5.1	no
t _{PHL}		Ь	2.1	12.9	1.4	7.5	1.3	5.4	0.9	4.6	ns
t _{PLH}	В	А	2.2	10.3	1.5	8.5	1.4	8	1	7.5	
t _{PHL}	В	A	2.2	8.5	1.4	7.5	1.3	7	0.9	6.2	ns
^t PHZ	DIR	А	3	8.1	3.1	8.1	2.8	8.1	3.2	8.1	no
t _{PLZ}	DIK		1.3	5.9	1.3	5.9	1.3	5.9	1	5.8	ns
t _{PHZ}	DIR	В	6.5	23.7	4.1	11.4	3.9	10.2	2.4	7.1	ns
t _{PLZ}	DIK	Ь	3.9	18.9	3.2	9.6	2.8	8.4	1.8	5.3	115
t _{PZH} †	DIB	۸		29.2		18.1		16.4		12.8	no
t _{PZL} †	DIR	Α		32.2		18.9		17.2		13.3	ns
t _{PZH} †	DIR	2		21.9		14.4		12.3		10.9	
t _{PZL} †	DIK	В		21		15.6		13.5		12.7	ns

[†]The enable time is a calculated value, derived using the formula shown in the section entitled *enable times* on page 16.

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switching characteristics over recommended operating free-air temperature range, V_{CCA} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	V _{CCB} = 1.8 V ± 0.15 V		V _{CCB} = 2.5 V ± 0.2 V		V _{CCB} = 3.3 V ± 0.3 V		V _{CCB} = 5 V ± 0.5 V		UNIT
	(INPUT)		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	^	В	2.1	15.5	1.4	8	0.7	5.8	0.7	4.4	ns
t _{PHL}	Α	Ь	2	12.6	1.3	7	0.8	5	0.7	4	115
t _{PLH}	В	А	1.7	8.3	1.3	6.4	0.7	5.8	0.6	5.4	ns
t _{PHL}	Ь	A	1.8	7.1	1.3	5.4	0.8	5	0.7	4.5	115
^t PHZ	DIR	А	2.9	7.3	3	7.3	2.8	7.3	3.4	7.3	ns
t _{PLZ}	DIK		1.8	5.6	1.6	5.6	2.2	5.7	2.2	5.7	115
^t PHZ	DIR	В	5.4	20.5	3.9	10.1	2.9	8.8	2.4	6.8	20
t _{PLZ}	DIK	Ь	3.3	14.5	2.9	7.8	2.4	7.1	1.7	4.9	ns
t _{PZH} †	DIB	٨		22.8		14.2		12.9		10.3	no
t _{PZL} †	DIR	Α		27.6		15.5		13.8		11.3	ns
t _{PZH} †	DIR	Б		21.1		13.6		11.5		10.1	20
t _{PZL} †	DIK	В		19.9		14.3		12.3		11.3	ns

[†]The enable time is a calculated value, derived using the formula shown in the section entitled enable times on page 16.

switching characteristics over recommended operating free-air temperature range, V_{CCA} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	V _{CCB} = ± 0.1		V _{CCB} = 2.5 V ± 0.2 V		V _{CCB} = 3.3 V ± 0.3 V		V _{CCB} = 5 V ± 0.5 V		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
^t PLH	А	В	1.9	15.1	1	7.5	0.6	5.4	0.5	3.9	
^t PHL	А	Ь	1.8	12.2	0.9	6.2	0.7	4.5	0.5	3.5	ns
^t PLH	В	Α	1.4	7.2	1	5.1	0.7	4.4	0.5	3.9	
^t PHL	В	A	1.7	7	0.9	4.6	0.7	4	0.5	3.5	ns
^t PHZ	DIR	^	2.1	5.4	2.2	5.4	2.2	5.5	2.2	5.4	ns
^t PLZ	DIK	Α	0.9	3.8	1	3.8	1	3.7	0.9	3.7	115
^t PHZ	DIR	В	4.8	20.2	2.5	9.8	1	8.5	2.5	6.5	ns
^t PLZ	DIK	Ь	4.2	14.8	2.5	7.4	2.5	7	1.6	4.5	115
t _{PZH} †	DIR	А		22		12.5		11.4		8.4	
t _{PZL} †	DIK	A		27.2		14.4		12.5		10	ns
t _{PZH} †	DIR			18.9		11.3		9.1		7.6	
t _{PZL} †	אוט	В		17.6		11.6		10		8.9	ns

[†] The enable time is a calculated value, derived using the formula shown in the section entitled *enable times* on page 16.

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{CCA} = V _{CCB} = 1.8 V	V _{CCA} = V _{CCB} = 2.5 V	V _{CCA} = V _{CCB} = 3.3 V	V _{CCA} = V _{CCB} = 5 V	UNIT
			TYP	TYP	TYP	TYP	
C wt	A port input, B port output		3	4	4	4	
C _{pdA} †	B port input, A port output	$C_L = 0$,	18	19	20	21	pF
C int	A port input, B port output	f = 10 MHz, $t_r = t_f = 1 \text{ ns}$	18	19	20	21	рг
C _{pdB} †	B port input, A port output]	3	4	4	4	

[†] Power-dissipation capacitance per transceiver

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power-up considerations

A proper power-up sequence always should be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies. Take the following precautions to guard against such power-up problems:

- 1. Connect ground before any supply voltage is applied.
- 2. Power up V_{CCA}.
- 3. V_{CCB} can be ramped up along with or after V_{CCA} .

typical total static power consumption (I_{CCA} + I_{CCB})

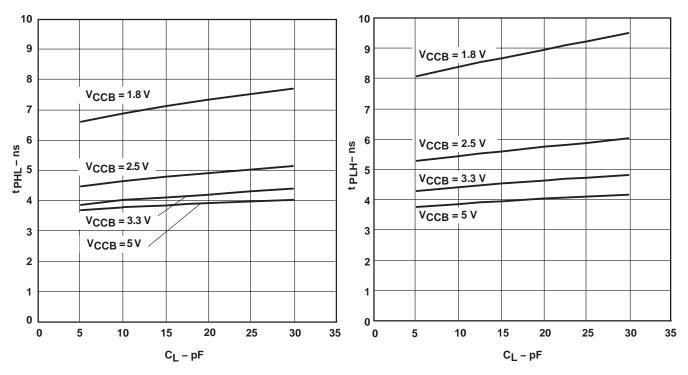
Table 1

V			VCCA			LINUT
VCCB	0 V	1.8 V	2.5 V	3.3 V	5 V	UNIT
0 V	0	<1	<1	<1	<1	
1.8 V	<1	<2	<2	<2	2	
2.5 V	<1	<2	<2	<2	<2	μΑ
3.3 V	<1	<2	<2	<2	<2	
5 V	<1	2	<2	<2	<2	

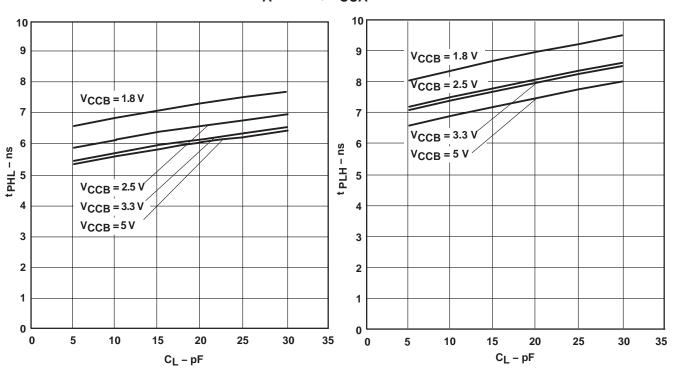
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TYPICAL CHARACTERISTICS

TYPICAL PROPAGATION DELAY (A TO B) vs LOAD CAPACITANCE $T_{A}=25^{\circ}\text{C},\,V_{CCA}=1.8\;\text{V}$



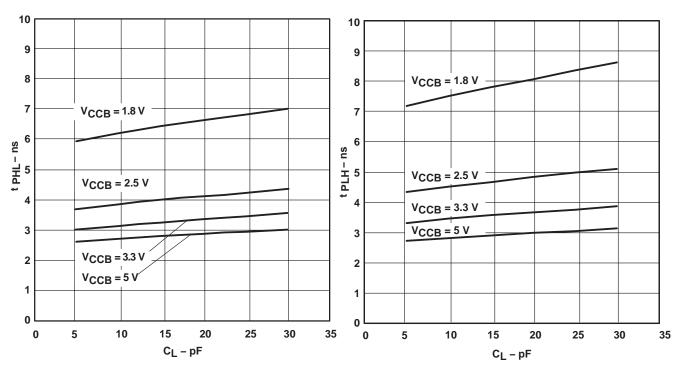
TYPICAL PROPAGATION DELAY (B TO A) vs LOAD CAPACITANCE $T_A = 25^{\circ}\text{C}$, $V_{CCA} = 1.8 \text{ V}$



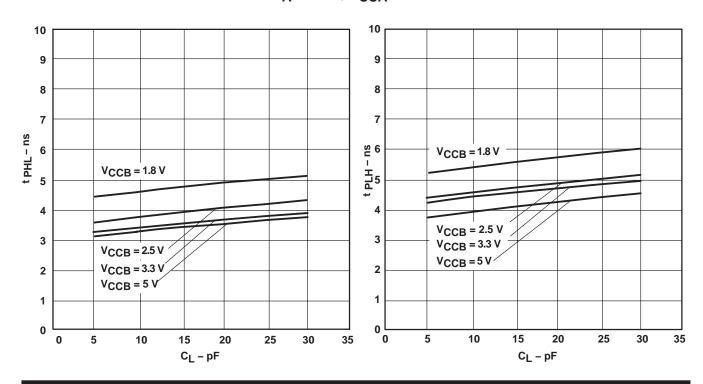


TYPICAL CHARACTERISTICS

TYPICAL PROPAGATION DELAY (A TO B) vs LOAD CAPACITANCE $T_A = 25\,^{\circ}\text{C},\, V_{\text{CCA}} = 2.5\,\,\text{V}$



TYPICAL PROPAGATION DELAY (B TO A) vs LOAD CAPACITANCE $\rm T_A = 25^{\circ}C,\, \rm V_{CCA} = 2.5\, \rm V$

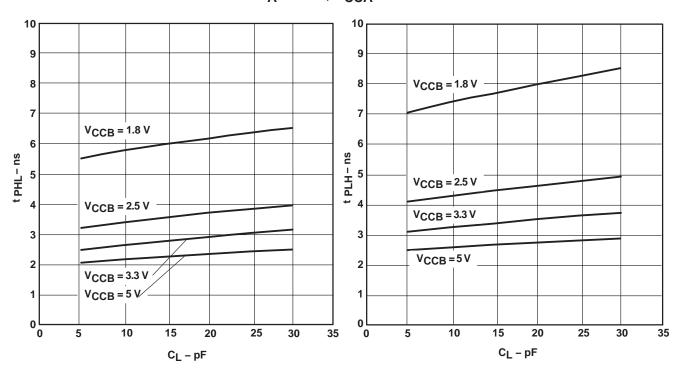




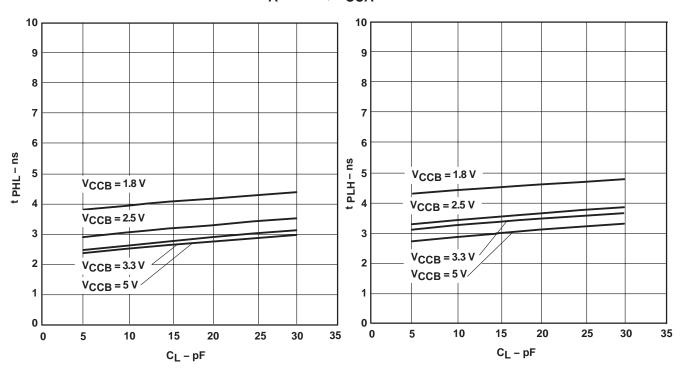
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TYPICAL CHARACTERISTICS

TYPICAL PROPAGATION DELAY (A TO B) vs LOAD CAPACITANCE $\rm T_A = 25^{\circ}C,\, \rm V_{CCA} = 3.3~\rm V$



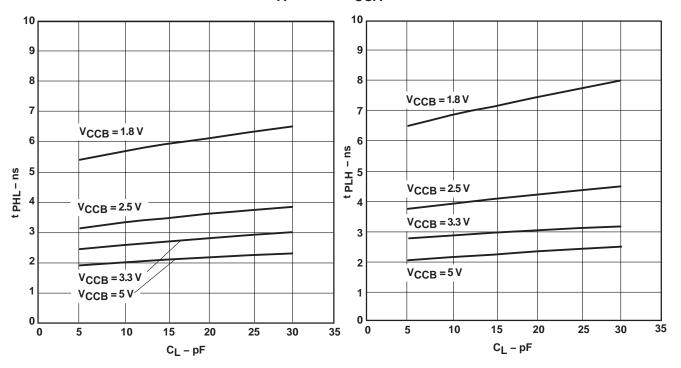
TYPICAL PROPAGATION DELAY (B TO A) vs LOAD CAPACITANCE $T_{A}=25^{\circ}\text{C},\,V_{CCA}=3.3\;\text{V}$



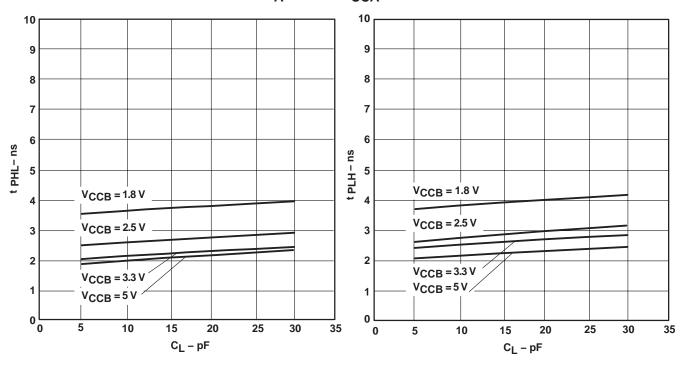


TYPICAL CHARACTERISTICS

TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE T_{A} = 25°C, V_{CCA} = 5 V



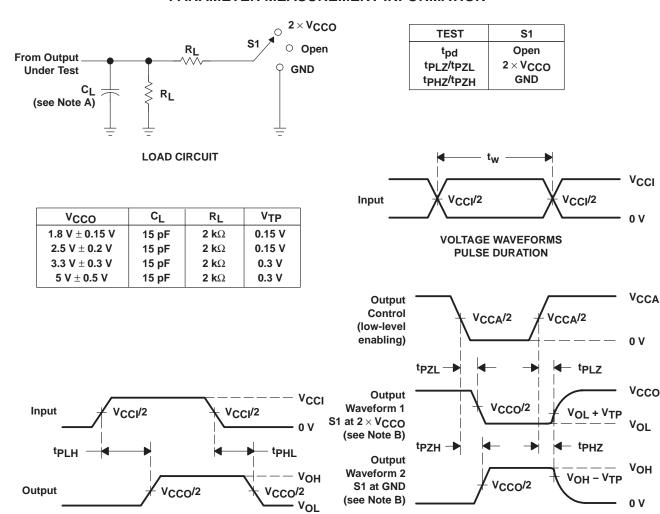
TYPICAL PROPAGATION DELAY (B TO A) vs LOAD CAPACITANCE T_{A} = 25°C, V_{CCA} = 5 V





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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C₁ includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

VOLTAGE WAVEFORMS

ENABLE AND DISABLE TIMES

- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{\Omega} = 50 \Omega$, $dv/dt \geq 1 V/ns$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. VCCI is the VCC associated with the input port.
- I. V_{CCO} is the V_{CC} associated with the output port.

VOLTAGE WAVEFORMS

PROPAGATION DELAY TIMES

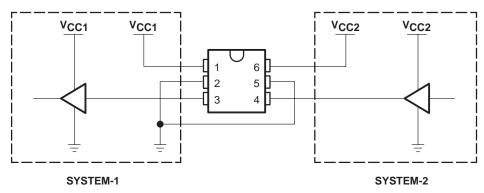
J. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms



APPLICATION INFORMATION

The following circuit is an example of the SN74LVC1T45 being used in a unidirectional logic level-shifting application.



PIN	NAME	FUNCTION	DESCRIPTION
1	VCCA	V _{CC1}	SYSTEM-1 supply voltage (1.65 V to 5.5 V)
2	GND	GND	Device GND
3	А	OUT	Output level depends on V _{CC1} voltage.
4	В	IN	Input threshold value depends on V _{CC2} voltage.
5	DIR	DIR	The GND (low level) determines B port to A port direction.
6	VCCB	V _{CC2}	SYSTEM-2 supply voltage (1.65 V to 5.5 V)

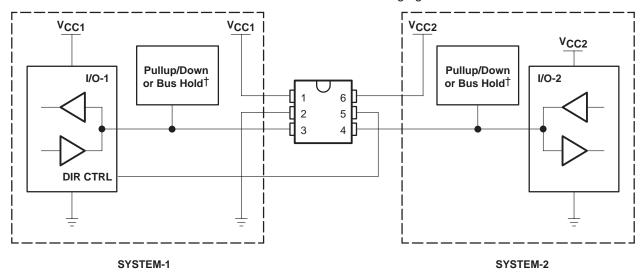
Figure 3. Unidirectional Logic Level-Shifting Application



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APPLICATION INFORMATION

Figure 4 shows the SN74LVC1T45 being used in a bidirectional logic level-shifting application. Since the SN74LVC1T45 does not have an output enable (OE) pin, the system designer should take precautions to avoid bus contention between SYSTEM-1 and SYSTEM-2 when changing directions.



Following is a sequence that illustrates data transmission from SYSTEM-1 to SYSTEM-2 and then from SYSTEM-2 to SYSTEM-1.

STATE	DIR CTRL	I/O 1	I/O 2	DESCRIPTION
1	Н	OUT	IN	SYSTEM-1 data to SYSTEM-2
2	н	HI-Z	HI-Z	SYSTEM-2 is getting ready to send data to SYSTEM-1. I/O-1 and I/O-2 are disabled. The bus-line state depends on pullup or pulldown.†
3	L	HI-Z	HI-Z	DIR bit is flipped. I/O-1 and I/O-2 still are disabled. The bus-line state depends on pullup or pulldown.†
4	L	OUT	IN	SYSTEM-2 data to SYSTEM-1

[†]SYSTEM-1 and SYSTEM-2 must use the same conditions, i.e., both pullup or both pulldown.

Figure 4. Bidirectional Logic Level-Shifting Application

enable times

Calculate the enable times for the SN74LVC1T45 using the following formulas:

- 1. t_{PZH} (DIR to A) = t_{PLZ} (DIR to B) + t_{PLH} (B to A)
- 2. t_{PZL} (DIR to A) = t_{PHZ} (DIR to B) + t_{PHL} (B to A)
- 3. t_{PZH} (DIR to B) = t_{PIZ} (DIR to A) + t_{PIH} (A to B)
- 4. t_{PZL} (DIR to B) = t_{PHZ} (DIR to A) + t_{PHL} (A to B)

In a bidirectional application, these enable times provide the maximum delay from the time the DIR bit is switched until an output is expected. For example, if the SN74LVC1T45 initially is transmitting from A to B, then the DIR bit is switched, the B port of the device must be disabled before presenting it with an input. After the B port has been disabled, an input signal applied to it appears on the corresponding A port after the specified propagation delay.





PACKAGE OPTION ADDENDUM

12-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC1T45DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DBVRE4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DBVTE4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DCKRG4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45DCKTE4	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1T45YEPR	ACTIVE	WCSP	YEP	6	3000	TBD	SNPB	Level-1-260C-UNLIM
SN74LVC1T45YZPR	ACTIVE	WCSP	YZP	6	3000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

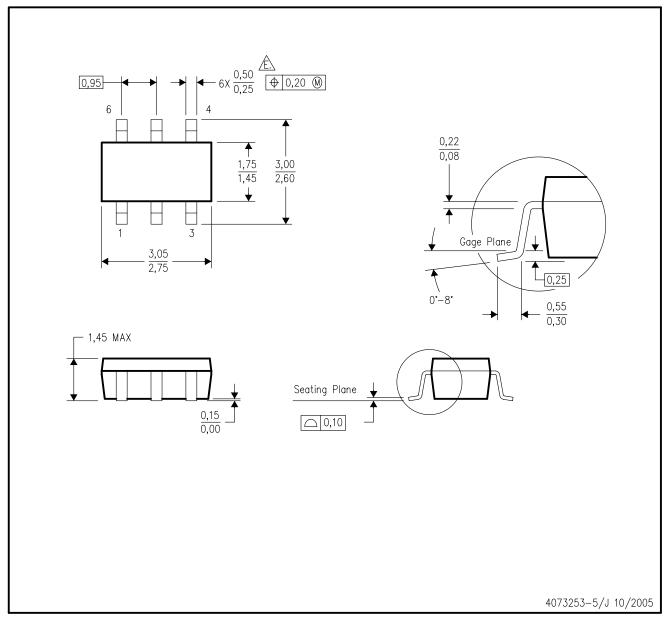
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



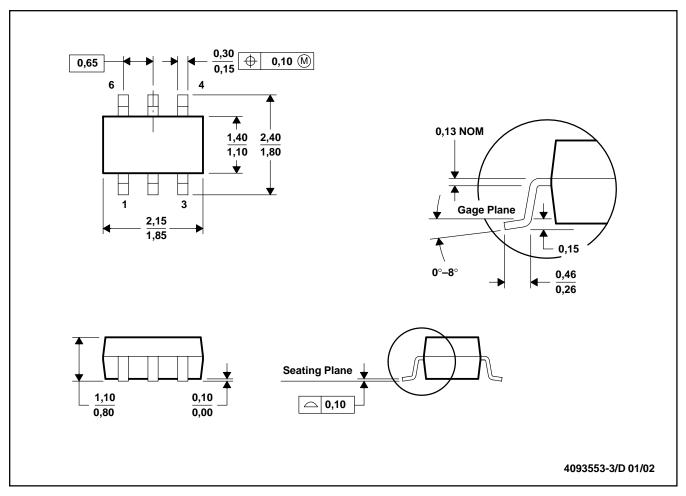
NOTES:

- A. All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- Falls within JEDEC MO-178 Variation AB, except minimum lead width.



DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE

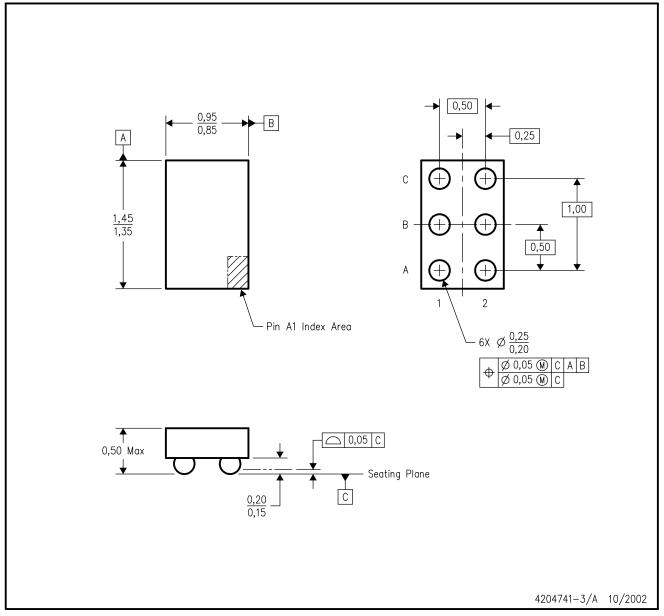


NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-203

YZP (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



NOTES:

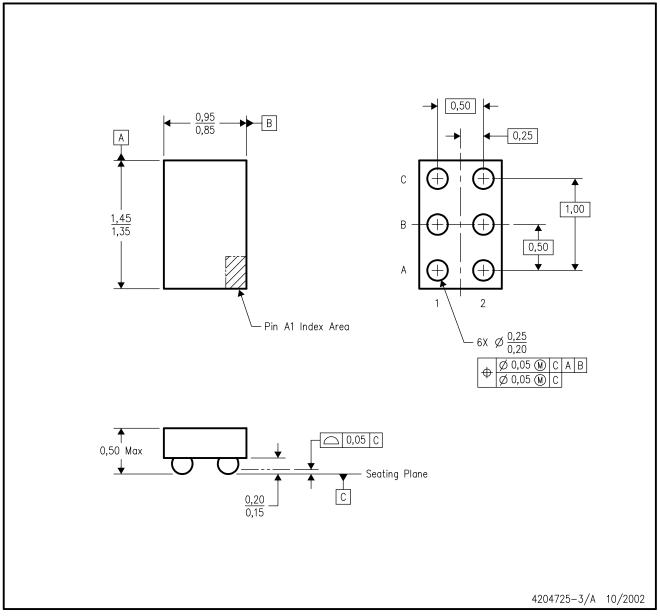
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. NanoFree™ package configuration.
- D. This package is lead-free. Refer to the 6 YEP package (drawing 4204725) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.



YEP (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. NanoStar™ package configuration.
- D. This package is tin-lead (SnPb). Refer to the 6 YZP package (drawing 4204741) for lead-free.

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